SEMI CONDUCTOR DEVICE AND SEMI CONDUCTOR MODULE USING THE SAME

ABSTRACT

A semi conductor device (71) of the present invention is made up of a semiconductor chip (1) and a single wiring tape (2) resembling a film carrier and including a wiring layer that has a preselected pattern. The wiring tape (2) is adhered to at least the top, bottom and one side of a semiconductor chip (1). The semiconductor device (71) has outer connecting portions arranged on the above surfaces of the chip (1). The semiconductor device (71) is comparable in package size with a bare chip. A semiconductor module having a plurality of such semiconductor devices arranged bidimensionally or tridimensionally achieves desirable electric characteristics while obviating the dense arrangement of a number of wirings.

Fig 1c